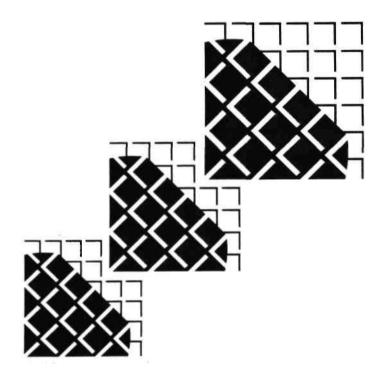
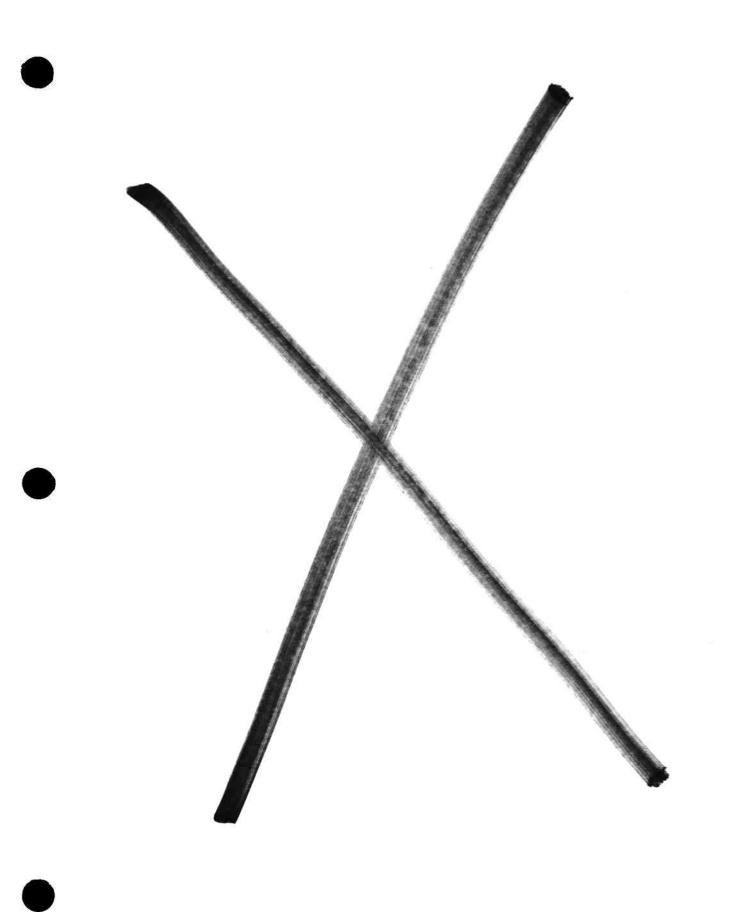
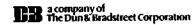
The Ninth Annual SEMICON/West Seminar: Stațus 1990



Dataquest Incorporated

May 23, 1990 Hotel Sofitel San Francisco Bay at Redwood Shores





THE NINTH ANNUAL SEMICON/WEST SEMINAR: STATUS 1990

May 23, 1990

AGENDA

7:00-8:00 a.m. Registration and Continental Breakfast

8:00 a.m. Welcome and Introduction

Joseph Grenier

Director

Semiconductor Equipment and Materials Service

8:10 a.m. Electronic Equipment Outlook and the Next PC Boom

Terrance Birkholz

Semiconductor User and Applications Group

8:40 a.m. Semiconductor Industry Status

David Angel

Vice President and Director Semiconductor Industry Service

9:10 a.m. New Manufacturing in the Submicron Decade

Mark Reagan

Semiconductor Equipment and Materials Service

9:40-9:55 a.m. Break

10:00 a.m. Some Key Performance Measures of the Semiconductor Equipment Industry

Joseph Grenier

Director

Semiconductor Equipment and Materials Service

10:30 a.m. Fab Equipment Trends in the '90s

Krishna Shankar

Semiconductor Equipment and Materials Service

11:00 a.m. Staying in the Materials Race through the '90s

Mark FitzGerald

Semiconductor Equipment and Materials Service

11:30 a.m. Trends in Packaging

Stan Bruederle Vice President

Components Group Consulting

Adjourn

SEMINAR INFORMATION

Location

Hotel Sofitel San Francisco Bay at Redwood Shores
223 Twin Dolphin Drive, Redwood City, California 94065
Telephone (415) 598-9000
1290 Ridder Park Drive, San Jose, CA 95131-2398 (408) 437-8000 Telex 171973 Fax (408) 437-0292

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1990 SEMICON/WEST SEMINAR QUESTIONNAIRE

In order to continually improve the Semiconductor Equipment and Materials SEMICON/West Seminar, we need to better understand your information needs. Please help us by completing the following questionnaire. We would appreciate it if you would list your company name and/or attach your business card.

1.	Is your company a Dataquest client?YesNo
2.	Which of the following best describes your company's primary activities?
	Semiconductor manufacturer
	Semiconductor equipment supplier, Front end, Back end
	Semiconductor materials supplier
	Other
	(Please specify)
3.	Which of the following best describes your position/title?
	CEO, President, Vice President
	Strategic Planning/Business Development
	Sales and Marketing Management
	Product Development/R&D/Engineering Management
	Other
	(Please specify)
4.	How did you learn about this seminar?
	The brochure was mailed directly to me
	Someone in my company gave me the brochure
	Someone from Dataquest called me
	Other
	(Please specify)

		<u> Highest</u>	;	Lowe	<u>:st</u>
How well did the seminar meet your	objectives	? 5	4 3	2 1	L
In the future, should the length o					
What is the best day and time to Day	hold the sem				
Please comment on this location?					
				<u> </u>	
Please rate the speakers and their	speech cont	cent:			
		Delivery <u>Lowest</u>		ch Cont est <u>Lo</u>	
Terrance Birkholz	5 4 3	2 1		3 2	
Dave Angel	5 4 3	2 1	5 4	3 2	1
Mark Reagan Joseph Grenier	5 4 3	2 1	5 4	3 2 3 2	1
Krishna Shankar	5 4 3	2 1	5 4	3 2	1
Mark FitzGerald	5 4 3 5 4 3 5 4 3	2 1	5 4	3 2	î,
Stan Bruederle	5 4 3	2 1	5 4	3 2	ī
Topics you would like to hear about	at next yea	ar's seminar	· :		_
Please use this space for your co	mments on ar	ny aspect of	our se	minar:	-
				-	- -

(Optional)





SEMICON/West Seminar May 23, 1990 Redwood City, California

List of Attendees

AG Associates Donald M. Yoshikawa, Marketing Manager

ASM International N.V. Herbert Lakens, Director Marketing

ATEQ Corporation Barry Cox, President

Monty Zach, Marketing Administrator

Air Products & Chemicals, Inc. Dean Duffy, International Business

Manager

Stephen Hensler, Commercial Manager

Bob Nolan

Robert Shay, Commercial Development

Manager

Airco/BOC Philip Blakey, Vice President of

Electronics

Applied Materials, Inc. Dana C. Ditmore, Vice President,

Customer Service Division

Michael George, Director of Marketing

Dennis Hunter, Director, Corporate

Development

Noella Kwan, Research Analyst David Orgill, Manager, Investor

Relations

Dave Reis

Aseco Corporation Ken Lee, Vice President Engineering

Ashland Chemical Company James A. Duquin, Vice President &

General Manager, Electronic & Lab Products

Assembly Technologies Joseph Savarese, Vice President and

General Manager

Bandgap Technology Corporation Volker Heilmann, Vice President &

General Manager

Bank of Boston Elizabeth Everett, Assistant Vice President Oscar Jazdowsky, Director Thomas A. Hannen, Assistant Vice Bank of the West President Les G. Polgar, Vice President, Marketing Bertram Laboratories, Inc. & Sales Lou Perrone, Vice President, Marketing & Branson International Plasma Corporation Technology Brooks Instruments Joseph Dille, Product Manager Harry Lund, Vice President, Sales Kanegi Nagai, President and Chief Cybeg Systems Executive Officer Daifuku U.S.A. Inc. Takehide Hiyashi, Section Manager Hajime Maeda Sam Nakajima, Sales Manager Jim Donahue, President Delta Design Inc. Dexter Electronic Materials Ron Benham, President DuPont Photomasks, Inc. Bob Machado, Technical Service Manager E.I. DuPont de Nemours & Company Neil Washburn, Senior Development Specialist, Specialty Polymer Division ESEC USA Inc. Gary Spray, Vice President and General

Eaton Corporation

Manager

Carl Noblitt, Director, Marketing Geoffrey Ryding, Vice President & Director, Marketing, Sales & Services, Semiconductors Edwards High Vacuum International

64 .

Ameeta Soni, Product Marketing Manager

Electro Scientific Industries, Inc.

Russ Schlager, Product Manager

Equitable Lomas Leasing Corporation

Chuck Beckmire, Vice President & Director, Vendor Programs
Louie Coffman, Executive Vice President, Operations
Dean Cuplin, Vice President, Manufacturer/Vendor Products
Paul Edstrom, Vice President, Equipment Steven Grundon, Vice President, Marketing Services
Colleen Lusian, Assistant Vice President, Equipment Evaluation
Mike Mardesich, Appraiser
John McEwen, Account Representative

FSI International

Walt Kalin, Director of Marketing Laurie Walker, Communications Manager

Ellie Sanchez, Market Research Manager

First Interstate Bank

Robin Apple Linda Ometer Pam Robichaux Marc J. Verissimo, Vice President

GCA Corporation

Gary A. Mezack, Vice President, Marketing

General Signal/Xynetics

Nancy McKereghan, Market Analyst Gordon C. Westwood, Vice President, Marketing

Genus, Inc.

Ron Dornseif, Vice President, Corp. Excellence Program William W.R. Elder, President and Chief Executive Officer Robert McGeary, Vice President, Marketing and Sales

Hewlett-Packard Company

James K. Lee, Procurement Engineer

Hughes Aircraft Company

Gordon Chang, Manager, DMS

Integrated Solutions

Rich Cimino, Director of Sales &

Marketing

Intel Corporation

٠:.

Joe Louie, Q & R Manager

Jacques J. Vuye, Manager, Competitive

Analysis

KTI Chemicals, Inc.

Dave Zaring, Technical Marketing Manager

Kobe Development Corporation

Takeo Tanaka, General Manager

Kokusai Electric Co., Ltd.

Noriaki Yamamoto, Assistant Marketing

Manager

Kulicke & Soffa Industries, Inc.

Ron Clunk, Director of Corporate

Marketing

Asuri Raghavan, Director of Business

Division

Kyocera America. Inc.

Chuck E. DeMars, Vice President,

Microelectronics Division

Lam Research Corporation

Henk Evenhuis, Senior Vice President,

Finance & CFO

Debbie McGovan, Manager, Investor

Relations

John Osborne, Senior Vice President,

Strategic Development

Liquid Air Corporation

Denis Rufin, Manager of Technology

Lumonics Corporation

Pat Austin, President, Marking Systems

Division

Materials Research Corporation

Irwin Grater, Director of Marketing

Matheson Gas Products

Pat Carlucci

*	`*
Mattson Technology, Inc.	Ralph Martin, Vice President of Engineering Brad Mattson, President
Meissner+Wurst GmbH+Co	· Jurgen Giessmann, Managing Director
Micro Mask .	Bob Jaynes, Corporate Vice President, Marketing & Sales Russ Weiss, Executive Vice President and COO
Mitel Corporation	Luc Gagnon, Product Marketing Manager
Mitel Semiconductor	Gord Harling, Director, Process R&D
Mitsubishi Semiconductor America Inc.	Tad Mizoguchi, President
Montgomery Securities	Jonathan Joseph Tom Thornhill, Vice President
NBK Corporation	Joseph Arruda, Director of Sales and Marketing
NCR Corporation	Timothy P. McCarthy, Director of . Manufacturing
Nikon Precision, Inc.	David Kettering, Product Line Manager
Oki Electric Industry Co., Ltd.	Jim Cantore, Manager, Strategic Marketing
Osaka Sanso Kogyo, Ltd.	Michael Solomon, General Manager Electric Gases, The BOC Group
Outokumpu Corporation	Asko Vehanen, Development Manager

Reed Sarver, Electronics Sales Manager

Pall Ultrafine Filtration Corp

Price Waterhouse Technology	Paul Turner, Director
Prism Technologies, Inc.	Bobby Greenberg, President Bob Williams
Prometrix Corporation	Steve Westrate, International Marketing Manager
Prudential-Bache Capital Funding	Mark Edelstone, Junior Semiconductor Analyst
Prudential-Bache Securities	Chad Keck, Managing Director
Ramtron Corporation	Jon Downing, Logistics & Acquisitions Manager
Rapro Technology, Inc.	Tom Kandris, Vice President, Sales/Service
Raychem Corporation	Charles K. Cheng, Marketing Manager
Rudolph Research	Richard L. Budzinski, Director of Sales
SEEQ Technology, Inc.	Michael Van Hoy, Vice President of Marketing
SEMATECH	Michael Stark, Competitive Analyst
Samsung Semiconductor & Tel. Co., Ltd.	S. L. Choi, Senior Planning Manager Kyung W. Kim, Planning Manager
Sandia National Laboratories	Douglas L. Weaver, Department Manager, 2130
Security Pacific Bank	Joe Foster, Vice President
Seiko Instruments USA, Inc.	Hiroshi Fukino, Chairman and Chief

Ŧ.,

Executive Officer

Semiconductor Services

Katherine B. Evans, Customer Relations

Semiconductor Systems, Inc.

Eric Hsu, Sales Manager

Signetics Corporation

Jim Bilham-Boult, Senior General Management Staff, Die Manufacturing Operations

Solid State Measurements, Inc.

John Snyder, Marketing Manager

Sumisho Electronic Systems, Inc.

Hiroshi Ishiwata, Sales & Marketing Manager

Swagelok Company

Donald Levengood, General Manager, Nupro Company David M. Simko, Manager, Marketing

Taiwan Semiconductor
Manufacturing Co., Ltd.

Klaus C. Wiemer, President

Temescal

Russell J. Hill, Director, Technology

Tencor Instruments, Inc.

Dale Guidoux, International Accounts
Manager
John Scott, Vice President
Roberta Wong, Marketing Communications
Manager

Teradyne, Inc.

James Prestridge, Vice President

Texas Instruments, Inc.

Pallab Chatterjee, Vice President, Corporate Staff Graydon Larrabee, Director, MMST Program

Therma-Wave, Inc.

Charles Shalvoy, President and Chief Operating Officer

Toppan Electronics USA Inc.

Teruo Hisano, President

Toshiba America Electronic Components, Inc.

Kin Tang, Product Marketing Engineer

Tosoh SMD, Inc.

Steven L. Bardus, Product Manager

Tracor Northern, Inc.

Robert Hirche, National Sales Manager,

Electron Beam Instruments

Ultratech Stepper, Inc.

Kay Mascoli, Director of Marketing & Research, Government Relations

Union Bank

Frank Hall, Vice President

Anthony Kwee, Assistant Vice President Ed Schultz, Regional Vice President

James Weber, Vice President

Union Carbide Chemicals & Plastics Co.

Mike Bilancetti
H. Parks Brame
Bill Gittere
Jan Maurits
Bob Ricciardi
James L. Young

Union Carbide Corporation

Thomas Nelson, Applications Manager,

Electronics

Walter Willett, National Sales Manager

Union Carbide Industrial Gases Inc.

Bill Schmeh, Region Sales Manager Thomas L. Singman, Marketing Manager

United Microelectronics Corporation

Alvis Ho Wei-Jyh Liu

Varian Associates

James Crosskill, Planning Specialist Steve Jensen, Vice President, Marketing

Watkins-Johnson Company

John F. Lunden, Manager, Commercial

Equipment Development

Weitek Corporation

Jim Gay, Manager, Business Development Westech Systems Inc.

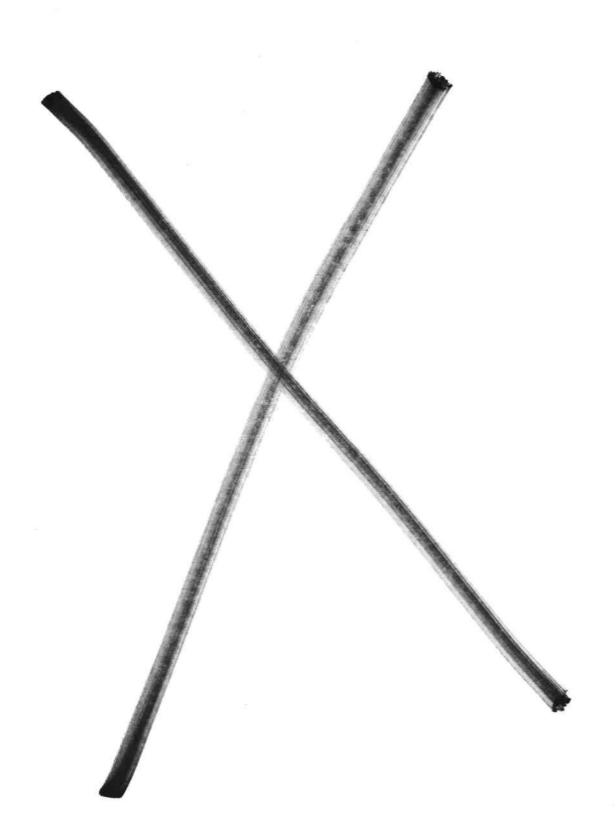
Dave Anderson, Marketing and Sales Manager

Zilog, Inc.

Michael Bradshaw, Vice President of Operations Larry Thomas

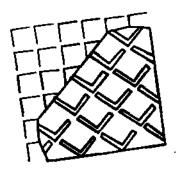
Zitel Corporation

Karl Schiavo, Purchasing Supervisor



Market Big and State

Dataquest's Ninth Annual SEMICON/West Seminar Status 1990 May 23, 1990



Electronic Equipment Outlook and the Next PC Boom

Terrance A. Birkholz

Industry Analyst
Semiconductor User and Applications Group
Dataquest Incorporated

AGENDA

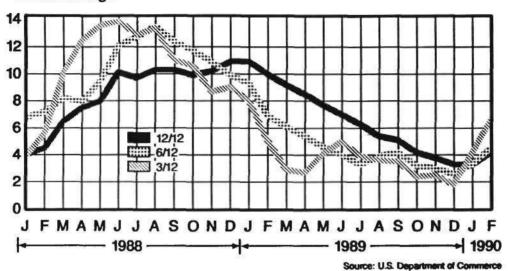
- Near-term outlook
- Long-term outlook
- Summary

NEAR-TERM OUTLOOK

U.S. COMPUTERS AND OFFICE EQUIPMENT

Shipments Growth (1988-1990)

Percent Change

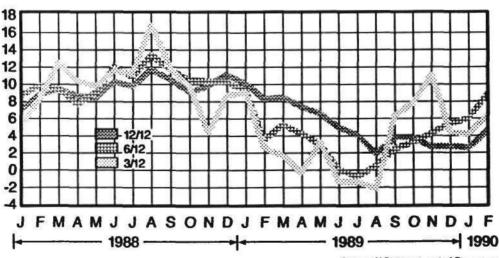


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U.S. COMPUTERS AND OFFICE EQUIPMENT

Orders Growth (1988-1990)

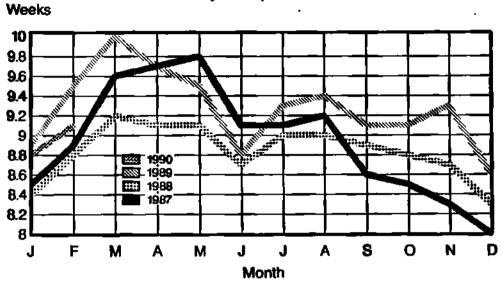
Percent Change



Source: U.S. Department of Commerce

U.S. COMPUTERS AND OFFICE EQUIPMENT

Inventory to Shipments Ratio



Source: U.S. Department of Commerce

Company of the contract of

U.S. COMMUNICATIONS EQUIPMENT

In February:

- Three-month-ended orders: 11.1% above year-earlier orders
- Three-month-ended shipments: 10.5% above year-earlier shipments
- Inventory at 9.9 weeks was 1.1 weeks less than February 1989

Dataquest expects:

- · Orders growth to stabilize
- · Shipments growth to remain brisk, then stabilize

U.S. INSTRUMENTS

In February:

- Three-month-ended orders: 6.1% above year-earlier orders
- Three-month-ended shipments: 3.6% above year-earlier shipments
- Inventory at 10.4 weeks was 0.4 week less than February 1989

Dataquest expects:

Upcoming months to be marked by relatively stable growth

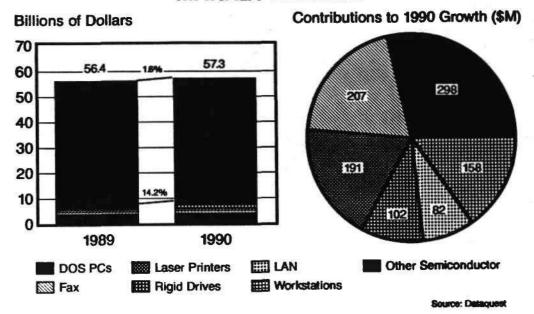
THE PERSON NAMED IN

ELECTRONIC EQUIPMENT PRODUCTION FORECAST

(Billions of Dollars)

	1989	1990	<u>%∆</u>
Total Worldwide	653.1	689.7	5.6
North America	269.2	285.0	5.8
Japan	181.1	183.7	1.4
Europe	149.0	159.6	7.1
Asia/Pacific	53.8	61.5	14.3

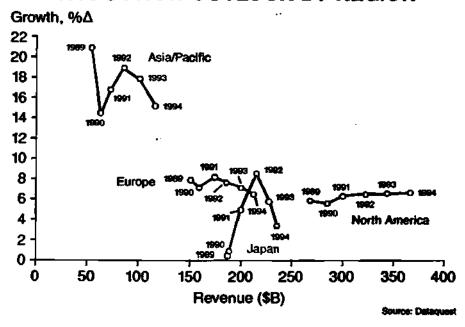
NEAR-TERM SEMICONDUCTOR MARKET DRIVERS



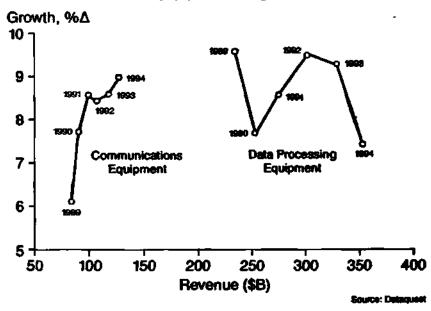
MARKS BELLEVIEW

LONG-TERM OUTLOOK

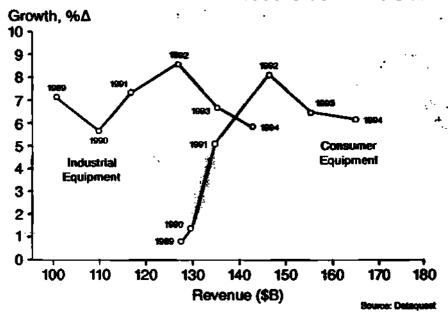
ESTIMATED WORLDWIDE ELECTRONIC EQUIPMENT PRODUCTION OUTLOOK BY REGION



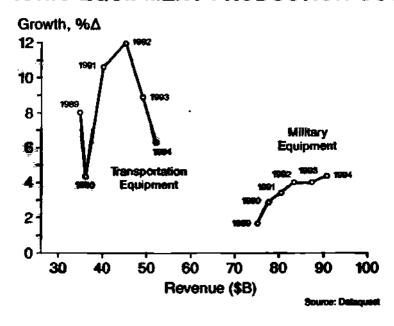
ESTIMATED WORLDWIDE ELECTRONIC PRODUCTION OUTLOOK



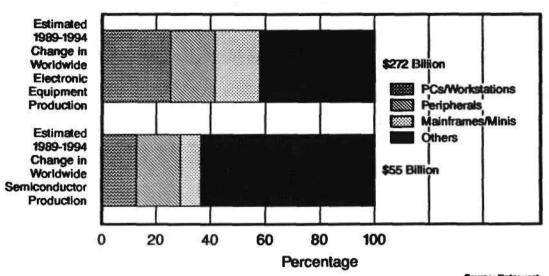
ESTIMATED WORLDWIDE ELECTRONIC EQUIPMENT PRODUCTION OUTLOOK



ESTIMATED WORLDWIDE ELECTRONIC EQUIPMENT PRODUCTION OUTLOOK



LONG-TERM SEMICONDUCTOR MARKET DRIVERS



Source: Detaquest

CHESTY AND CHESTOR

WORLDWIDE LONG-TERM OUTLOOK

- Electronic equipment production growth to accelerate to 7.3% in 1991 from 5.4% in 1990
- Growth to peak at 8.6% in 1992
- Noncomputer semiconductor growth up sharply
- Greatest semiconductor growth opportunities within data processing – smart peripherals and subsystems
- Asia/Pacific and Japan are fastest-growing regions in 1992
- Rising trade protectionist sentiment and production cost minimization necessitate evenly distributed, regionalized production
- Eastern Europe and China emerging markets (?)

SUMMARY

In the near term:

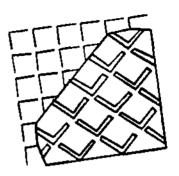
- 5.4% worldwide electronic equipment production growth forecast in 1990
- Semiconductor consumption fueled by a few healthy application markets
 - (0.7%) worldwide overall semiconductor consumption growth
 - 3.6% worldwide nonmemory semiconductor consumption growth

in the long term:

- 8.6% worldwide electronic equipment production peak growth forecast in 1992
- PC boom extending to smart peripherals

a company of The Dun & Bradstreet Corporation

Dataquest's Ninth Annual SEMICON/West Seminar Status 1990 May 23, 1990



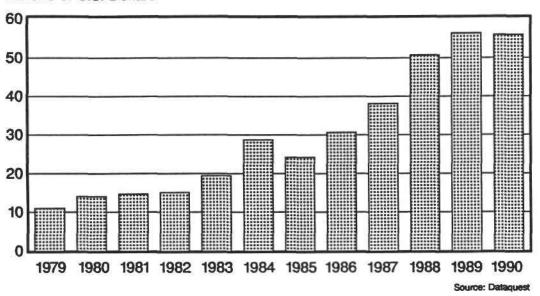
Semiconductor Industry Status

David L. Angel

Vice President and Director of Worldwide Research Semiconductor Industry Service Dataquest Incorporated

WORLDWIDE SEMICONDUCTOR MARKET

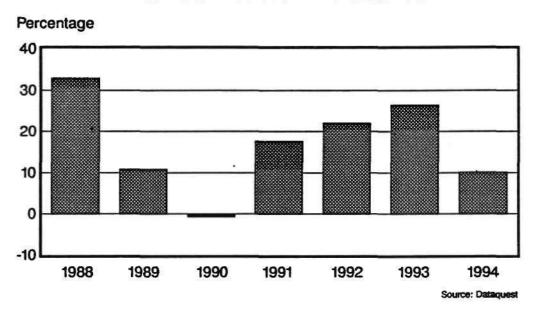




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Forecast: 1990 and Beyond

WORLDWIDE SEMICONDUCTOR INDUSTRY REVENUE GROWTH FORECAST



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OUTLOOK

- Peak of next boom will be in 1993
- Market will surpass \$100 billion in 1993
- MOS memory will remain fastest-growing segment
- Bipolar digital memory and logic will continue to decline due to BiCMOS alternative
- Stabilizing factors now occurring
- 1990: A year of challenges

REGIONAL OUTLOOK

North America

- CAGR 1989-1994 ~ 15% (1990 down 3%)
- Slow, steady growth
- Slower GNP growth in 1990 than in 1989
- Workstations, PCs, laser printers, rigid disk drives are market drivers
- Will grow slightly faster than Japan through 1994
- Will remain second-largest market through 1994
- Consolidation will become significant

Source: Dataquest

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REGIONAL OUTLOOK

Japan

- CAGR 1989-1994 ~ 13.5% (1990 down 2.0%)
- Flat market in 1990
- Changing from export-driven to domestic demand-driven economy
- Will remain largest market through 1994
- Will be slowest-growing market through 1994
- · Fax machines, laser printers, PCs are driving markets
- China's political instability hurting Japanese exports
- GNP will remain strong in 1990

REGIONAL OUTLOOK

Europe

- CAGR 1989-1994 ~15% (1990 up 2%)
- PCs will continue to be market driver
- Fierce PC and DRAM competition from Asian suppliers
- GNP growth will be faster than in U.S., although U.K. is suffering
- Long-term growth equal to North America
- Will maintain market size position at #3 through 1994, in spite of Asia/ROW

Source: Dataquest

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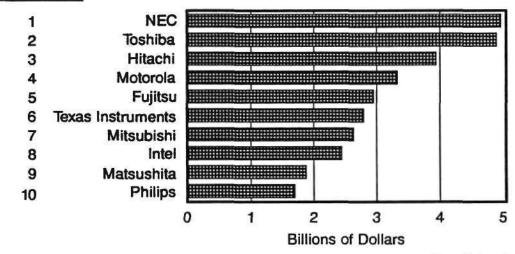
REGIONAL OUTLOOK

Asia/Pacific

- CAGR 1989-1994 ~ 20.1% (1990 up 6.0%)
- Personal computers are the name of the game in Taiwan
- · Mergers, acquisitions, marketing channels are key
- Domestic demand picking up volume from decelerating exports
- Hong Kong companies moving some operations to Thailand and Malaysia
- Fastest-growing market through 1994
- Will remain smallest market through 1994

TOP 10 MERCHANT SEMICONDUCTOR COMPANIES' WORLDWIDE REVENUE IN 1989

1988 Rankings

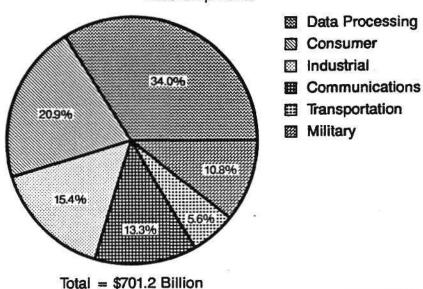


Source: Dataquest

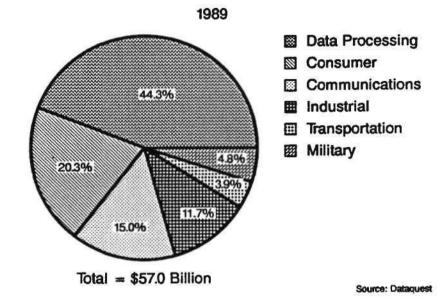
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WORLDWIDE ELECTRONICS MARKETS

1989 Shipments



WORLDWIDE SEMICONDUCTOR CONSUMPTION BY APPLICATION MARKET

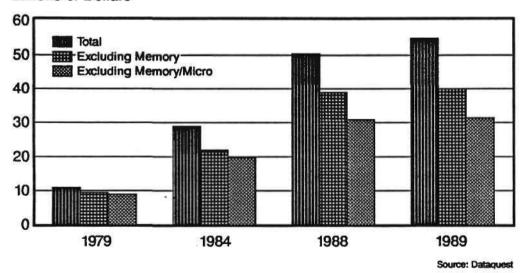


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1989: ANATOMY OF A MARKET

Memory and Micros: The Industry Drivers

Billions of Dollars

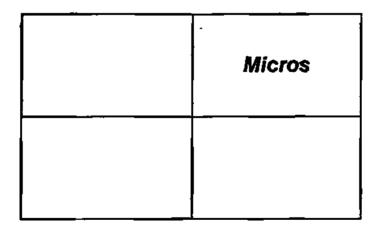


PRODUCT FORECASTS

Memory	Micros
ASIC	Analog

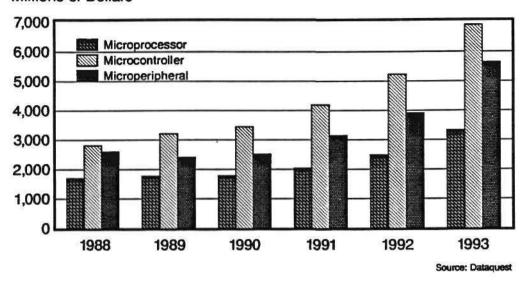
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PRODUCT FORECASTS



WORLDWIDE MOS MICROPROCESSOR FORECAST

Millions of Dollars



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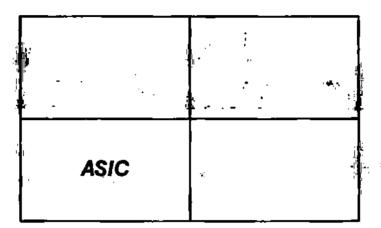
1989 WORLDWIDE MOS MICROCOMPONENTS TOP 10 SUPPLIERS

(Millions of Dollars)

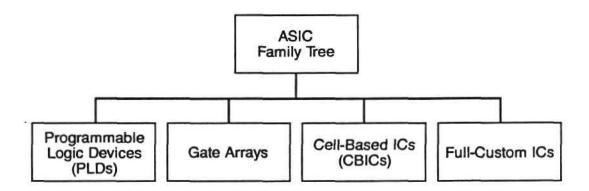
1989 Ranking	1988 Ranking	(1988 Revenue	1989 Revenue	Percent Change	1989 Market Share
1	1	Intel	1,835	1,929	5%	23.5%
2	2	NEC	790	937	19%	11.4%
3	2 3	Motorola	699	803	15%	9.8%
4	4	Hitachi	525	554	6%	6.8%
5	5	Mitsubishi	381	435	14%	5.3%
6	6	Toshiba	346	407	18%	5.0%
7	7	Texas Instruments	234	252	8%	3.1%
8	8	Matsushita	230	217	(6%)	2.6%
9	13	Chips & Technologies	130	216	66%	2.6%
10	9	Fujitsu	202	211	4%	2.6%

Source: Dataquest

PRODUCT FORECASTS



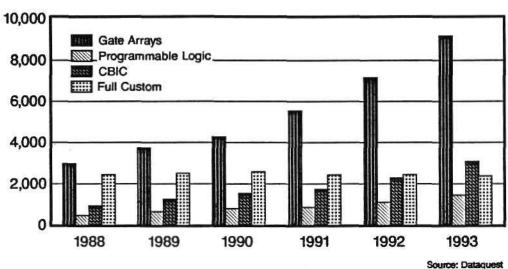
ASIC FAMILY TREE



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ESTIMATED WORLDWIDE ASIC CONSUMPTION BY TECHNOLOGY

Millions of Dollars



1989 WORLDWIDE ASIC TOP 10 SUPPLIERS

(Millions of Dollars)

1988 Rank	1989 Rank	•	Gate Arrays	CBICs	PLDs	Total
1	1	Fujitsu	62 1	48	0	669
2	2	NEC	. 548	27	0	575
3	3	LSI Logic	420	37	0	457
4	4	Toshiba	299	101	0	400
5	5	Advanced Micro Devices	24	0	314	400 338
Ĝ	6	AT&T	46	257	0	303
7	7	Texas instruments	28	155	91	274
8	8	Hitachi	263	6	0	269
10	9	VLSI Technology	47	122	Ó	169
9	10	National	106	12	42	160
_		Total	2,402	765	447	3,614

Note: 1989 revenue estimates are prefiminary.

Source: Dataquest

SETTRESUMS CHESTON

ASIC TRENDS

Gate Arrays

- Significant cut in design starts
- Heavy revenue impact from chip sets
- More complex PLDs will affect gate arrays
- · Severe price competition
- BiCMOS: the new frontier
- RISC processors going on-chip

Source: Dataquest

ASIC TRENDS

Cell-Based ICs

- Tied closely to application markets
- Good growth forecast
- Will not catch gate arrays
- Mixed-mode designs grow in popularity
- · Testability a major challenge
- RISC processors to become critical cell in CBIC library

Source: Dataquest

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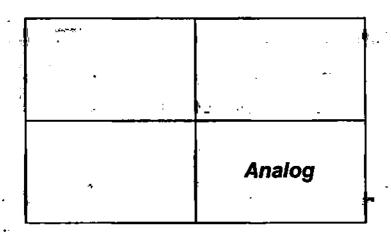
ASIC TRENDS

PLDs

- PLDs will become alternative to gate arrays
 - Watch for offshore competition
- Market driven by diverse architectures and innovative applications
 - Growth in complex PLDs
- Most new ideas coming from new entrants

Source: Dataquest

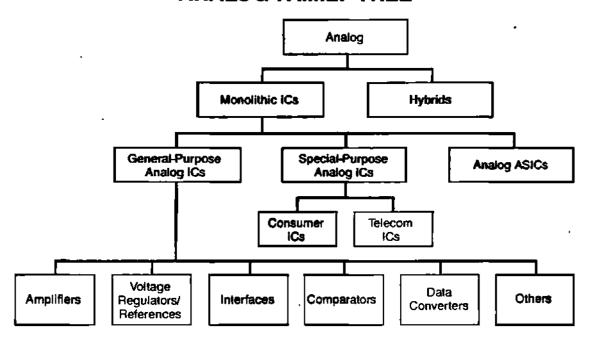
PRODUCT FORECASTS



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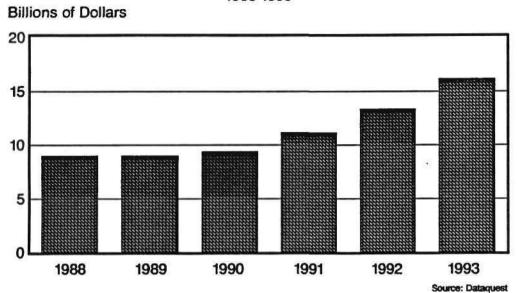
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ANALOG FAMILY TREE



WORLDWIDE ANALOG IC FORECAST

1988-1993



1989 WORLDWIDE ANALOG TOP 10 SUPPLIERS

		(Millions of Dollars)				1989
1989 Ranking	1988 Ranking		1988 Revenue	1989 Revenue	Percent Change	Market Share
1	1	Toshiba	569	572	(1%)	6.1%
Ž	· 2	National Semiconductor	540	558	3%	5.9%
3	5	Sanvo	471	530	13%	5.6%
4	3	Philips `	466	522	12%	5.6%
5	7	Motorola	425	445	5%	4.7%
6	6	Texas Instruments	426	417	(2%)	4.4%
7	4	NEC	469	415	(12%)	4.4%
8	11	SGS-Thomson	352	393	12%	4.2%
9	9	Mitsubishi	395	384	(3%)	4.1%
10	8	Matsushita	423	376	(11%)	4.0%

Source: Dataquesi

517052JMS 6427756ANG

THE ANALOG MARKET

- Rivals memory as largest IC segment
- Less cyclical than digital products
- Long life cycles
- Design intensive rather than process intensive
- Very fragmented in:
 - Products
 - Markets
 - Suppliers
 - Applications

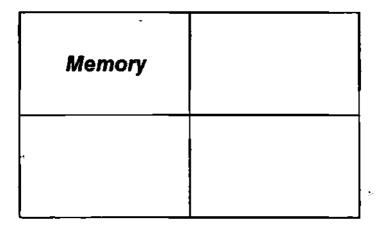
THE ANALOG MARKET

Analog is key to . . .

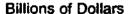
- Automotive electronics
- HDTV and consumer electronics
- Smart power and home automation
- High-resolution computer graphics and video
- Disk drive electronics
- Mixed-signal ASICs

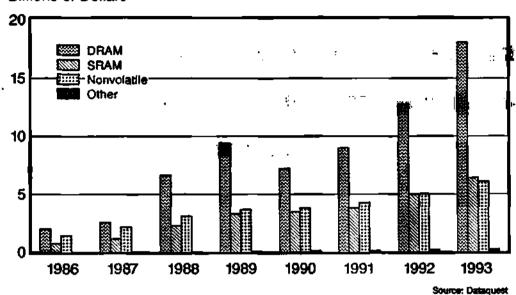
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PRODUCT FORECASTS



MOS MEMORY FORECAST





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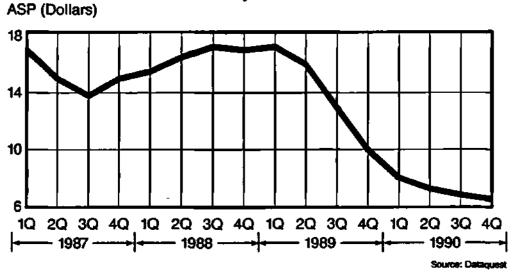
1989 WORLDWIDE MOS MEMORY

TOP 10 SUPPLIERS

(Millions of Dollars)						
1989 Ranking	1988 Ranking		1988 Revenue	1989 Revenue	Percent Change	Mårket Share
1	1	Toshiba	1,516	1,918	27%	11.7%
2	2	NEC	1,490	1,739	17%	10.6%
3	3	Hitachi	1,114	1,534	38%	9.4%
4	4	Fujitsu	1,067	1,265	19%	7.7%
5	5	Mitsubishi	966	1,161	20%	7.1%
6	6	Texas Instruments	834	1,095	31%	6.7%
7	7	Samsung	650	935	44%	5.7%
8	10	Sharp	344	476	38%	2.9%
9	9	Oki Semiconductor	353	473	34%	2.9%
10	8	Intel	392	433	10%	2.6%

ESTIMATED WORLDWIDE 1Mb DRAM PRICING

Quarterly: 1987-1990



0817646 (AB) 04/27/50-JA/6

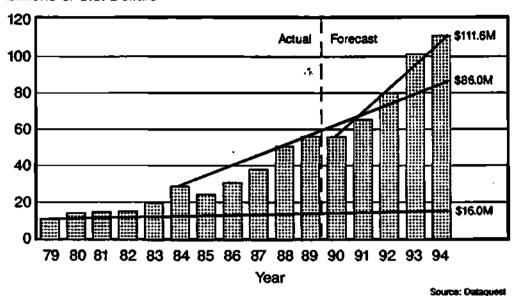
1990 OUTLOOK FOR 1Mb DRAMs

- First quarter oversupply
- Continued price erosion
- Possible political intervention
- Throttle-back of DRAM production
- Increased availability of SRAMs and PSRAMs
- Potential supply glitch during recovery
- Difficult 4Mb introduction

Source: Dataquest

WORLDWIDE SEMICONDUCTOR MARKET

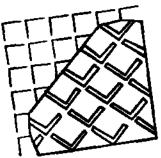
Billions of U.S. Dollars



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Dataquest's Ninth Annual SEMICON/West Seminar Status 1990 May 23, 1990



New Manufacturing in the Submicron Decade

Mark T. Reagan

Semiconductor Equipment and Materials Service
Dataquest Incorporated

AGENDA

- Line geometries
- 200mm manufacturing
- New fabs
- · Cost of a fab
- Capital spending

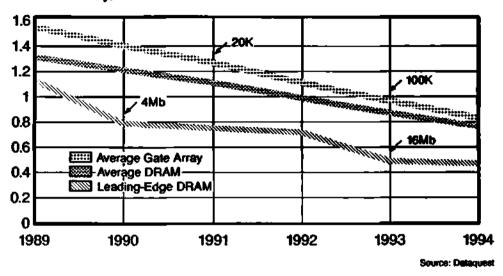
MARKET CHEST PARTY NEW

AGENDA

• Line geometries

CONVERGING TECHNOLOGIES: ASIC AND DRAM LINE GEOMETRIES

Line Geometry, Microns



HERETAL CHROSES

THE ONE-MICRON BARRIER

- 79 submicron lines worldwide
- Submicron lines represent 10.4 percent of all installed fab lines
- All 200mm lines have minimum linewidths at or below one micron

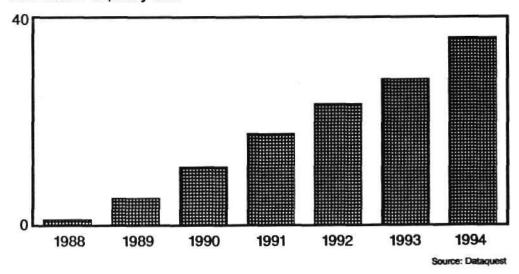
AGENDA

- Line geometries
- 200mm manufacturing

10000007 MG 05/04/90:REA

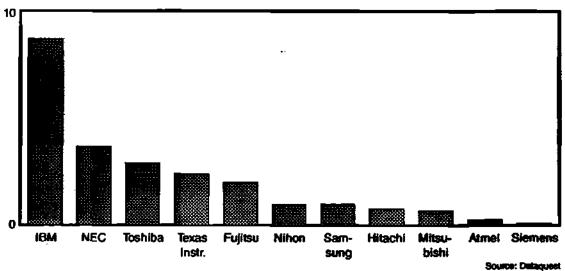
RUNNING TOTAL OF 200mm CAPACITY PER YEAR

Four-Week Capacity MSI



TOTAL 200mm CAPACITY BY COMPANY BY THE END OF 1992





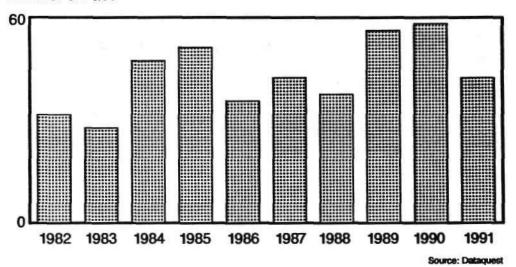
AGENDA

- Line geometries
- 200mm manufacturing
- New fabs

ESTIMATED NEW FAB LINES WORLDWIDE

R&D and GaAs Not Included

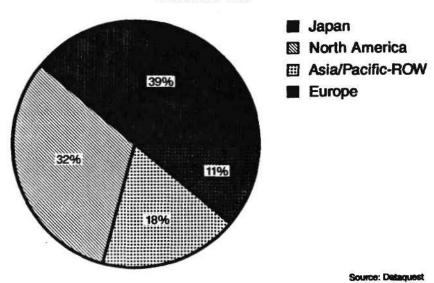
Number of Fabs



BOSSOCIE MIG GAZBANOTREA

NEW CAPACITY BY REGION

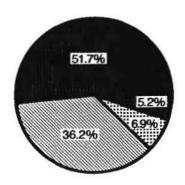
1990 and 1991



NEW SUBMICRON CAPACITY BY REGION

1990 and 1991

- 49% of total capacity will be submicron
- · Submicron portion is split as follows:



- Japan
- North America
- Europe
- Asia/Pacific-ROW

Source: Dataquest

AMERICA BASE BASES FEEL

NEW PLAYERS IN JAPAN

- Asahi Micro Systems
- Honda
- Isuzu
- Kawasaki Steel
- Kobe Steel
- Nippon Steel

- Nissan Motor
- NKK Steel
- Sumitomo Metal Mining
- TDK
- Toyota

AGENDA

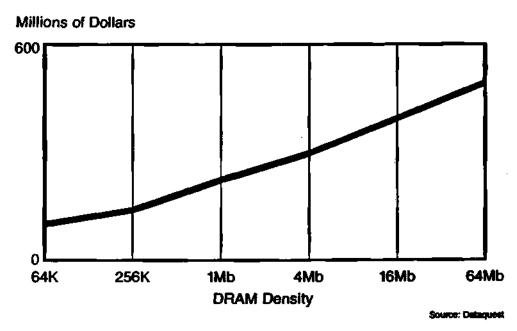
- Line geometries
- 200mm manufacturing
- New fabs

ŀ.

· Cost of a fab

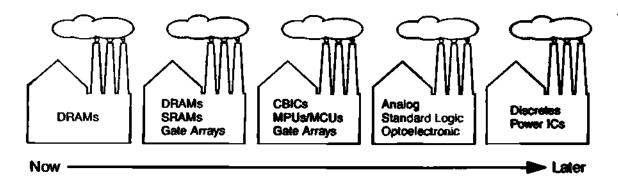
SHARE AND ANDRESEA

ESTIMATED COST OF A NEW DRAM FAB



FAB COST AMORTIZED OVER BOTH TIME AND PRODUCT

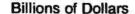
Span of 12 to 15 Years

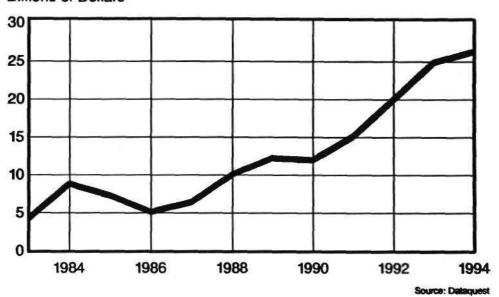


AGENDA

- Line geometries
- 200mm manufacturing
- New fabs
- · Cost of a fab
- Capital spending

WORLDWIDE CAPITAL SPENDING FORECAST

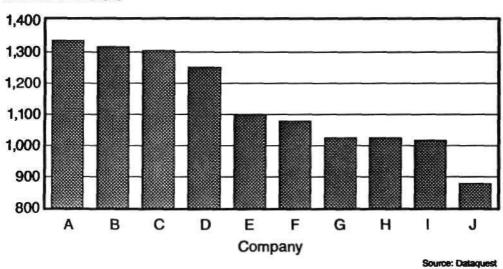




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ESTIMATED TOP 10 SEMICONDUCTOR CAPITAL SPENDING, 1994

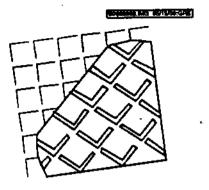
Millions of Dollars



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Some Key Performance Measures of the Semiconductor Equipment Industry

Joseph Grenier

Semiconductor Equipment and Materials Service Dataquest Incorporated

AGENDA

- Three key performance measures of the semiconductor equipment industry
- Status of the industry

0914565E

THREE KEY PERFORMANCE MEASURES

- Operating income
- R&D expenditures
- Sales per employee

OPERATING INCOME

Net sales

- Cost of sales
- SG&A expense
- R&D expenditures

Operating income

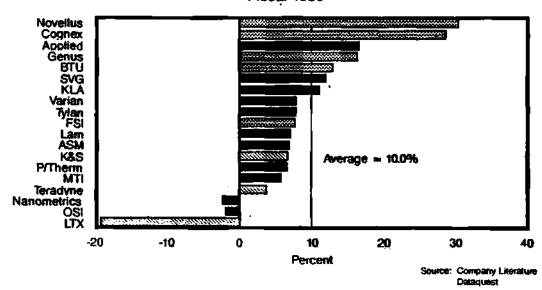
- Interest expense (income)
- Extraordinary items
- Income taxes

Net income

Charles and Street State

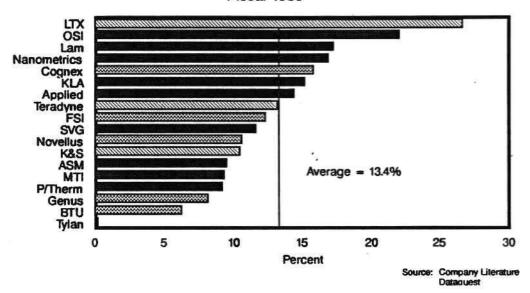
OPERATING INCOME AS PERCENT OF SALES





R&D EXPENDITURES AS PERCENT OF SALES

Fiscal 1989



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OPERATING INCOME PLUS R&D

A Pool of Funds

Net sales

- Cost of sales
- SG&A expense
- R&D expenditures

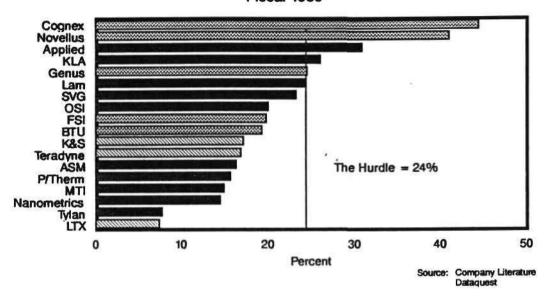
Operating income

Operating Income + R&D Expenditures Equals A Pool of Funds that Can Be Traded Off

Source: Dataquest

OPERATING INCOME PLUS R&D EXPENDITURES AS PERCENT OF SALES

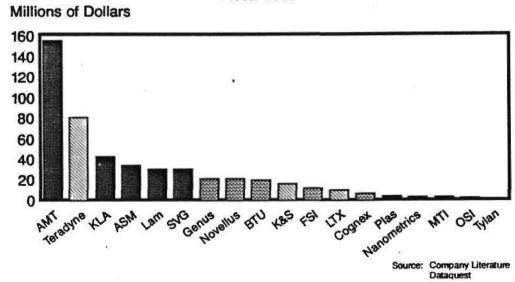
Fiscal 1989



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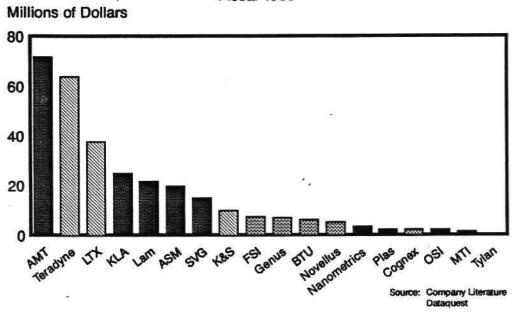
OPERATING INCOME PLUS R&D EXPENDITURES

Fiscal 1989



R&D EXPENDITURES

Fiscal 1989

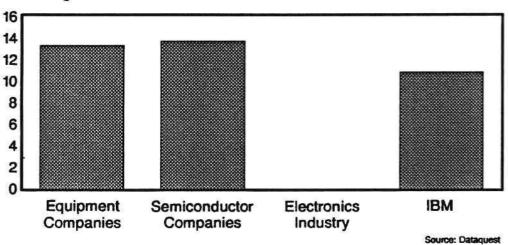


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HOW DO EQUIPMENT COMPANIES STACK UP?

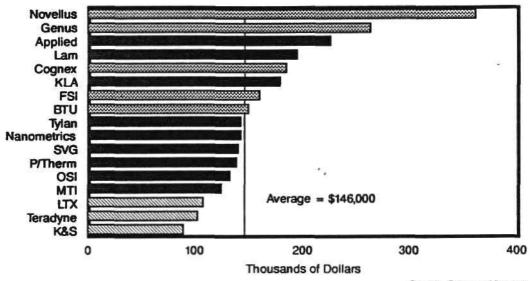
1989 R&D Expenditures - U.S. Companies

Percentage of Sales



SALES PER EMPLOYEE

Fiscal 1989

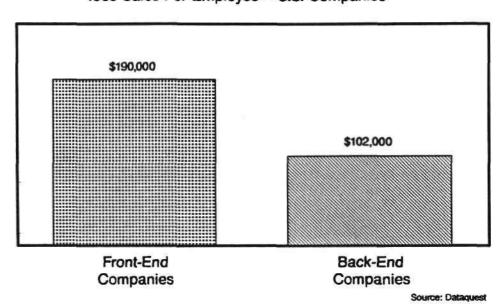


Source: Company Literature Dataquest

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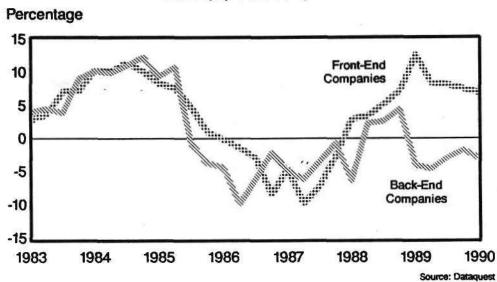
FRONT-END VS. BACK-END COMPANIES

1989 Sales Per Employee - U.S. Companies



NET INCOME AS PERCENT OF SALES

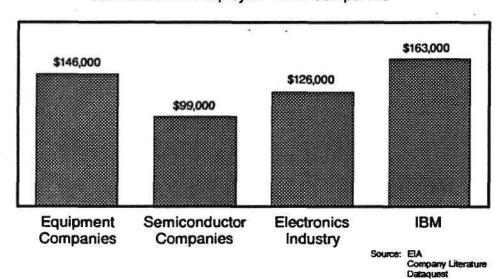
Front-End vs. Back-End U.S. Equipment Companies



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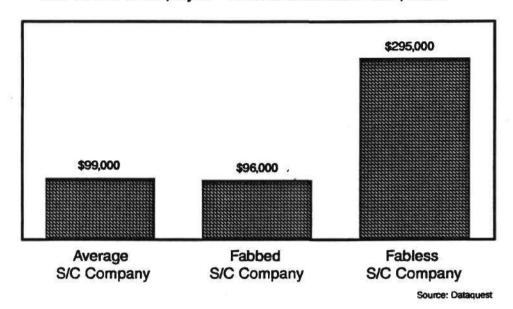
HOW DO EQUIPMENT COMPANIES STACK UP?

1989 Sales Per Employee - U.S. Companies



THE FABULOUS FABLESS

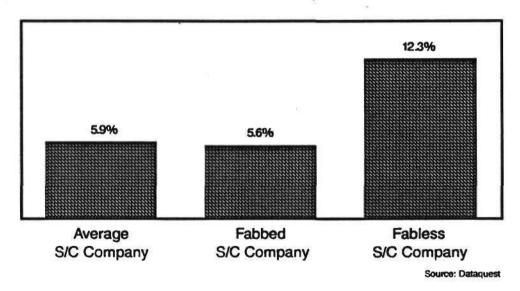
1989 Sales Per Employee - U.S. Semiconductor Companies



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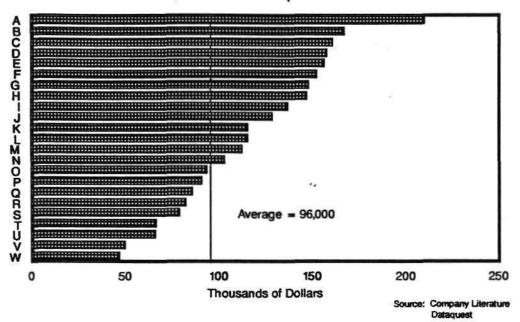
THE FABULOUS FABLESS

1989 Net Income as Percent of Sales – U.S. Semiconductor Companies



1989 SALES PER EMPLOYEE

U.S. Semiconductor Companies with Fabs

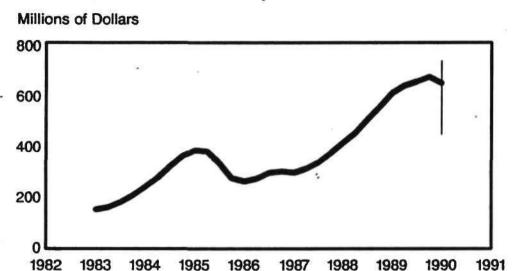


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Status of the Industry

EQUIPMENT COMPANY SALES TRENDS

Sales by Quarter



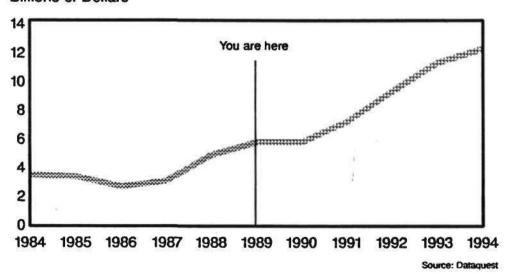
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Source: Dataquest

ESTIMATED WAFER FAB EQUIPMENT MARKET

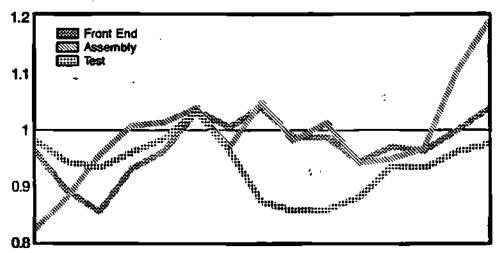
Worldwide

Billions of Dollars



SEMICONDUCTOR EQUIPMENT BOOK-TO-BILL RATIO

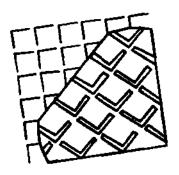
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Jan Feb Mar Apr May June July Aug Sep Oct Nov Dec Jan Feb Mar

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Wafer Fab Equipment Trends in the 1990s

Krishna Shankar
Semiconductor Equipment and Materials Service
Dataquest Incorporated

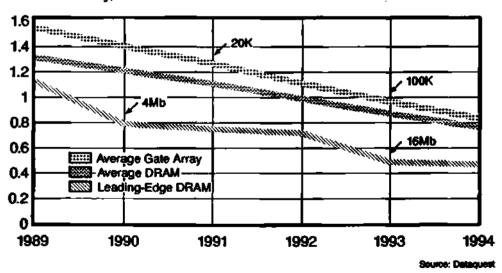
AGENDA

- Forces driving the fab equipment market in the 1990s
- Fab equipment market and technology trends
- Integrated processing market trends
- Future scenarios for fab equipment configuration
- Conclusions

MARKET THE MARKET

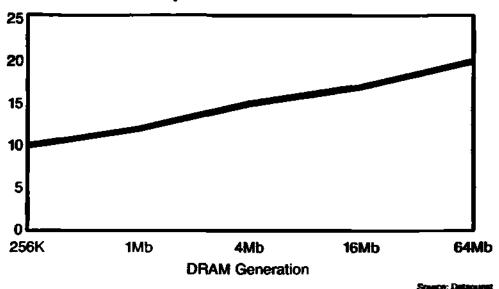
CONVERGING TECHNOLOGIES: ASIC AND DRAM LINE GEOMETRIES

Line Geometry, Microns



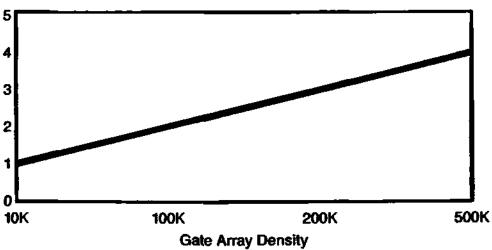
DRAMATIC INCREASE IN MASK/ETCH LAYERS

Number of Mask/Etch Layers



ASIC FABS DRIVE INTERCONNECT TECHNOLOGY

Number of Interconnect Levels



MICROPROCESSORS AS TECHNOLOGY DRIVERS

Chip Feature	1989	1990
Transistor Count	283,000	580,000
Technology	1.4µ CMOS	0.95μ CMOS
Clock Speed	32 MHz	61 MHz
Instruction Execution	29 mips peak	58 mips peak

Source: ISSCC 1990

16Mb DRAM AS TECHNOLOGY DRIVER

IBM at the Leading Edge

Feature

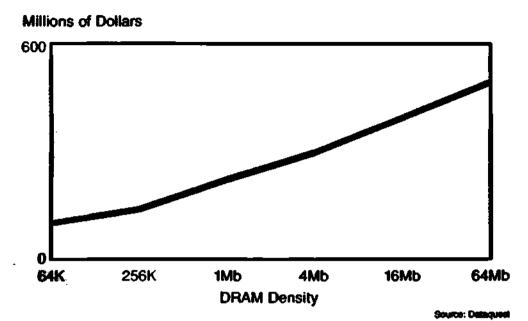
- 0.5-micron CMOS technology
- Deep UV lithography
- Excimer laser lithography
- 0.15-micron shallow junctions
- Tungsten plugs
- Lithography cluster
- Diffusion cluster
- . Thin films cluster

Comment

- Uses deep trench capacitor
- Step-and-scan tool
- 245nm excimer laser stepper
- Titanium silicide used
- Blanket tungsten etchback
- Integrated track and steppers
- Integrated thermal processing
- Integrated deposition/etch

Source: IBM

ESTIMATED COST OF A NEW DRAM FAB



AGENDA

- Forces driving the fab equipment market in the 1990s
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- Conclusions

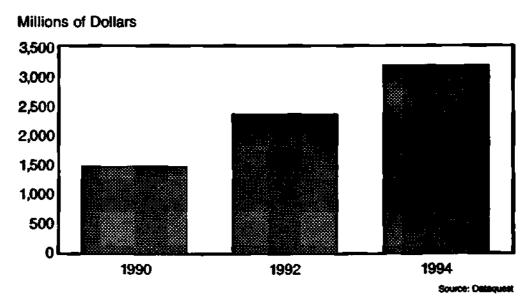
FAB EQUIPMENT MARKET AND TECHNOLOGY TRENDS

Engines Driving Submicron Processes

- Lithography management
- Thin films management

CHARLET BY BARRACKS

FOR THE 1990s



LITHOGRAPHY

Trends for the 1990s

- Interest reemerging in mix-and-match
 - 5:1 steppers with projection aligners
 - 5:1 steppers with 1:1 steppers
- Future mix-and-match strategy
 - I-line with e-beam
 - Where does this leave excimer laser and x-ray aligners?
- Two compact SORs soon to see first "light"
- New e-beam machines being introduced

Source: Datequest

PROPERTY OF THE PERSON NAMED IN

STEPPER TRENDS FOR THE 1990s

Keep Your Eye on I-Line

- G-line may fade faster than expected
- · A lot of activity in i-line
 - Japanese semiconductor manufacturers very interested in i-line
 - Stepper manufacturers introducing new systems
- I-line lens heating problem is solved
- I-line advantages
 - More depth of focus
 - More process latitude
 - Good for two generations of DRAMs

FAB EQUIPMENT MARKET AND TECHNOLOGY TRENDS

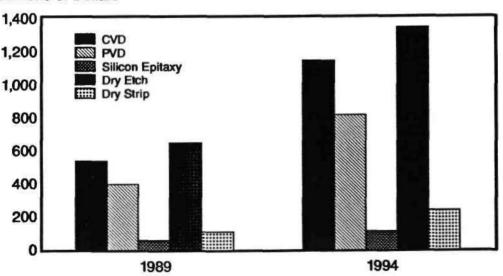
Engines Driving Submicron Processes

- Lithography management
- Thin films management

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THIN FILMS MARKET TRENDS FOR THE 1990s

Millions of Dollars



INTERCONNECT TRENDS FOR THE 1990s

- More than half the cost of submicron processes in the 1990s will be due to use of multilevel interconnect technology
- The choice of the optimum interconnect scheme, together with the appropriate processing equipment and materials, will be crucial to cost-effective submicron manufacturing

Source: Dataquest

PROPERTY OF STREET

CVD EQUIPMENT

Trends for the 1990s

- Development of cost-effective, productionworthy CVD processes
- Selective tungsten, aluminum, and copper for submicron processes
- ECR CVD for low-temperature, planarized dielectrics
- Integration of CVD into cluster tools

PVD EQUIPMENT

Trends for the 1990s

- Incorporation of PVD with CVD into cluster tools
- Growth of sputtering equipment market with three- and four-level metallization
- Excimer reflow of sputtered aluminum?

Source: Ontaquest

DRY ETCH EQUIPMENT

Trends for the 1990s

- High-selectivity, low ion damage equipment development
- Low-temperature etch processes for submicron processes
- In situ particle monitoring, plasma diagnostics
- Refinements to ECR and MERIE etch equipment

AGENDA

- Forces driving the fab equipment market in the 1990s
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THE PROBLEM

- Increasingly complex submicron processes are more sensitive to process-related defects
- Availability of reliable thin films deposition and etch equipment is a bottleneck in cost-effective submicron processing

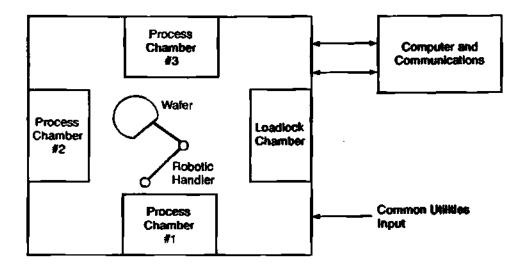
THE SOLUTION: INTEGRATED PROCESSING SYSTEMS -THE WAVE OF THE '90s

- Advantages of integrated processing systems:
 - In situ film deposition and etch
 - Lower defects
 - Faster turnaround time
 - Ease of automation
- Today's rigid multichamber tools (RMTs) are precursors to tomorrow's flexible cluster tools (FCTs)
- FCTs will integrate areas such as dry clean, CVD, PVD, dry etch, RTP, and silicon epi

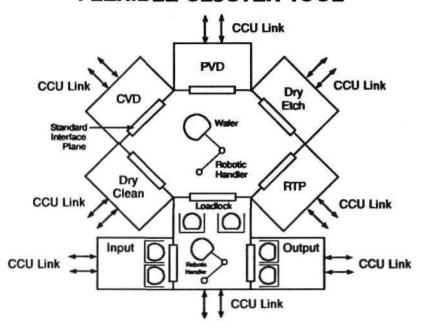
Source: Dataquest

AND COLUMN TO SERVICE AND COLUMN

SCHEMATIC OF A RIGID MULTICHAMBER TOOL



SCHEMATIC OF A FLEXIBLE CLUSTER TOOL



ANCHORES DAY DESCRIPTION

INTEGRATED PROCESSING SYSTEMS

Some Future Market Scenarios

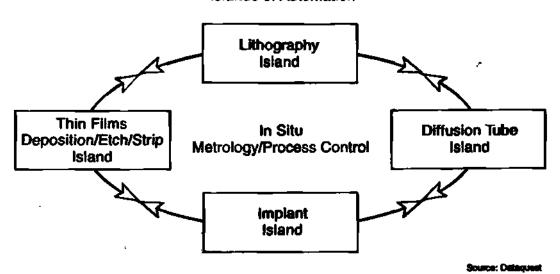
- New players: Wafer handling platform vendors, systems integrators, service companies?
- Synergistic partnership among equipment vendors
- Big, vertically integrated device companies will procure modules and assume ownership
- Emergence of "super" equipment vendors offering one-stop hardware, process, and service
- Timely, practical, worldwide standards fail to develop: The status quo prevails!

AGENDA

- Forces driving the fab equipment market in the 1990s
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FAB EQUIPMENT TRENDS FOR THE 1990s

Islands of Automation



AGENDA

- Forces driving the fab equipment market in the 1990s
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- Conclusions

Mark Brandson

CONCLUSIONS

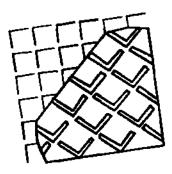
- Skyrocketing costs of submicron fabs
- Fab equipment industry in consolidation
- Lithography and interconnects drive technology
- Increasing process and equipment integration
- Fab equipment industry faces a momentous decade

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SALISA DIE GIANI III

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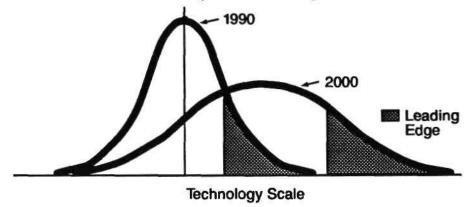
Staying in the Materials Race through the '90s

Mark FitzGerald

Semiconductor Equipment and Materials Service
Dataquest Incorporated

LEADING-EDGE TECHNOLOGY

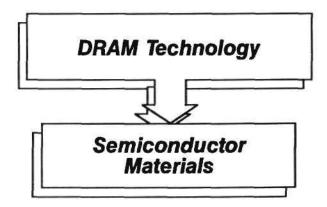
Leading-edge technology today will be the middle of the pack in the year 2000



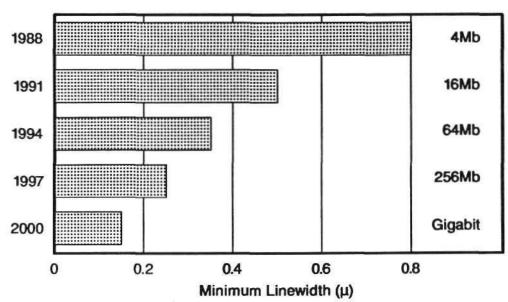
Source: Dataquest

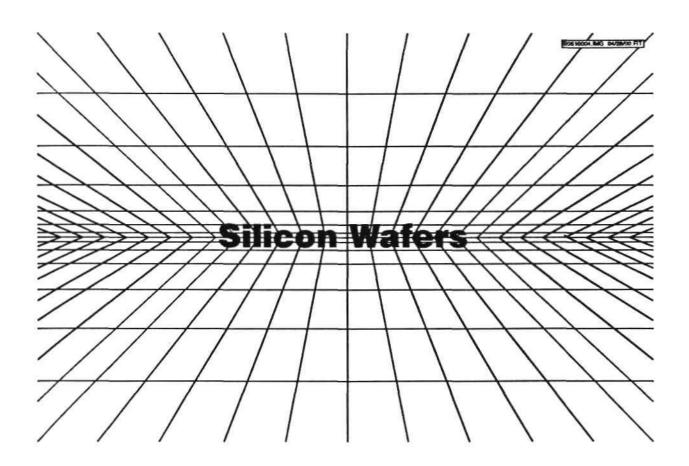
BOS HOUSE BAG 02/10/10:FIT

SETTING THE PACE . . .



THE MILESTONES





SILICON WAFER SIZE TRENDS

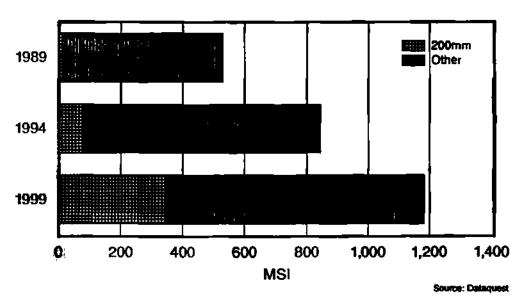
•		1991 16Mb			2000 Gigabit
Wafer Size (mm)	150	200	200	200	250
Wafer Size (inches)	6	8	8	8	10

Source: Dataquest

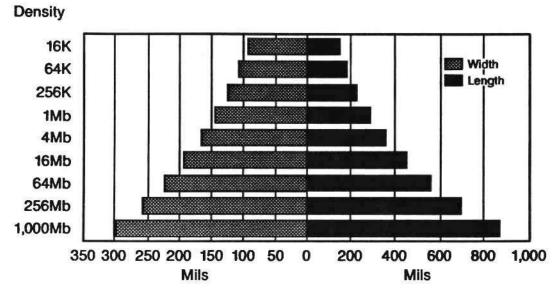
CONTRACTOR OF THE PARTY OF THE

SILICON WAFER SIZE DISTRIBUTION

North America



DRAM DIE DIMENSIONS



Source: ISSCC Technical Papers

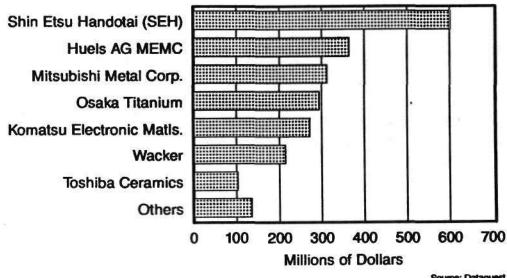
SINTERON MAIS SEPTOMOFIT

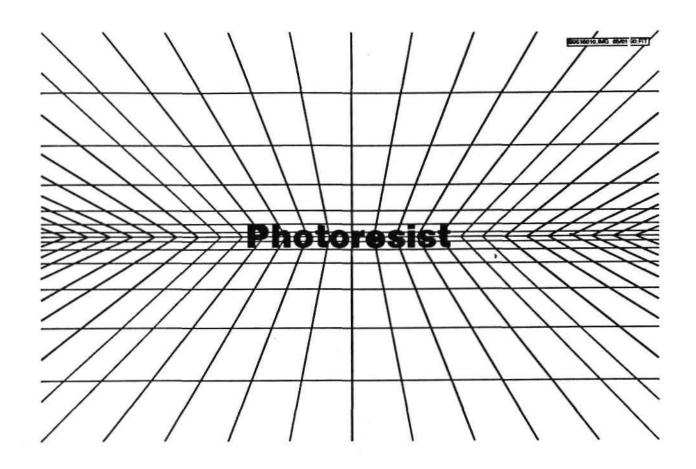
HURDLES FOR SILICON WAFER MANUFACTURERS

- Invest in 200mm wafer equipment
- Expand epitaxial wafer capacity (64Mb)
- · Meet tighter specs: flatness, resistivity

THE COMPETITORS

Worldwide Sales





PHOTORESIST TRENDS

	1988	1991	1994	1997	2000
	4Mb	16Mb	64Mb	256Mb	Gigabit
Photoresist Type	G-line	G-line	DUV	DUV X-ray	X-ray

Source: Dataquest

BANGES THE BENDESTAL

PUSH TO EXCIMER

- G-line the technology of the 1980s
- G-line systems continue to improve
 - Alignment systems
 - High N.A. lenses
 - Wide-field lenses
- Prevailing g-line strategy
 - Push g-line to limits
 - Excimer laser steppers
 - I-line an interim technology

PUSH TO I-LINE

- G-line may fade faster than expected
- · A lot of activity in i-line
 - Japanese semiconductor manufacturers very interested in i-line
 - Stepper manufacturers introducing new systems
- 1-line lens heating problem is solved
- I-line advantages
 - More depth of focus
 - More process latitude
 - Good for two generations of DRAMs

Source: Dataquest

CONTRACTOR OF THE PARTY

X-RAY RESISTS

- Current market is insignificant
 - R&D evaluation
 - No production
- X-ray resist volume anticipated in 1995
 - 2 years after linewidth crosses 0.4 micron (1993)
 - 256Mb DRAMs

HURDLES FOR PHOTORESIST MANUFACTURERS

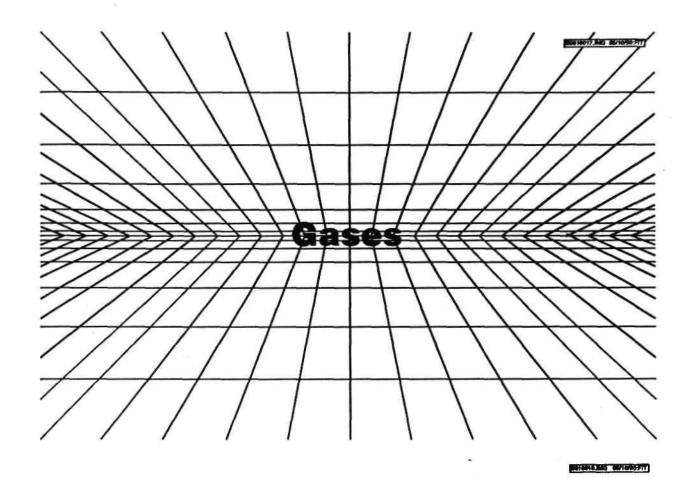
- Position company for change at excimer and the x-ray stepper introduction
- High degree of technical support
- Globalization

PRINCES OF STREET

TOP 10 RESIST SUPPLIERS, 1988

(Estimated Revenue, Millions of Dollars)

Company	Worldwide U.S.	
1. Tokyo Ohka	\$ 70	\$ 7
2. Shipley	45	25
3. Hunt	36	17
4. Hoechst	15	10
5. KTI	14	9
6. JSR	9	0
7. Dynachem ,	6	5
8. Ciba-Geigy	5	1
9. Macdermid	3	3
10. Baker	2	2
Total	\$205	\$79
		Course: Dataman

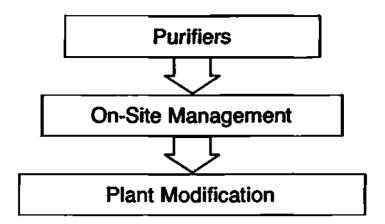


GASES TRENDS

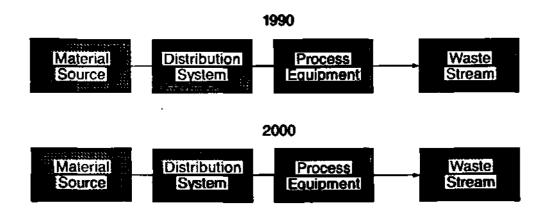
	1988	1997	2000
Liquid Process	35%	10%	0
Gaseous Process	65%	90%	100%
Killing Defect			
Size (µm)	0.15	0.05	0.03

Source: Graydon Larrabee Texas Instruments

THE MOVE TO HIGHER PURITY



VENDORS' RESPONSIBILITY FOR MAJOR SEGMENTS OF GAS SYSTEMS

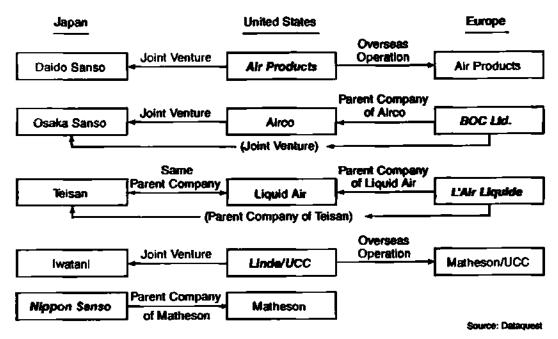


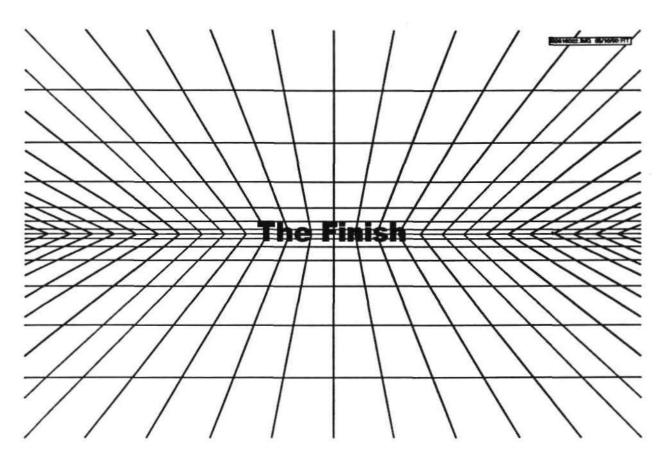
PLANTS PRODUCING HIGHER PURITY

- Capital cost
- Operating cost
- Plant output reduced

THE PERSON

GAS COMPANY INTERRELATIONSHIPS





BIGGES BAG GENERALITY

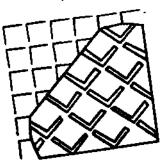
CONCLUSION

- Shift in technology
- Closer materials vendor-equipment-DRAM manufacturing relationship
- Large capital investment

Dataquest

a company of The Dun & Bradstreet Corporation

Dataquest's 9th Annual SEMICON/West Seminar May 23, 1990



Trends in Packaging: The Drive toward High-Density Interconnect

Stan Bruederle

Vice President
Components Group Consulting
Dataquest Incorporated

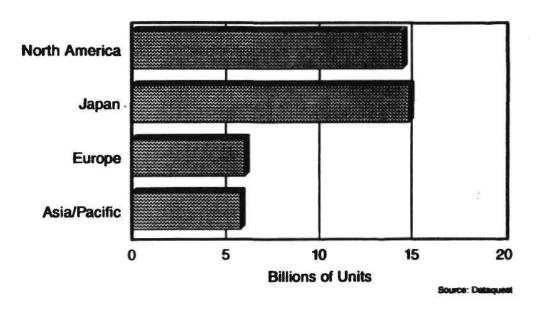
AGENDA

- Worldwide IC package market
- Emerging technologies analysis
- Applications demand analysis and forecast
- Strategic issues and opportunities
- Summary

AGENDA

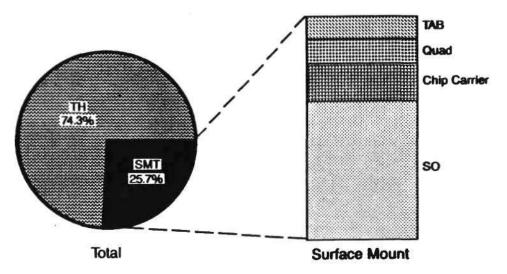
• Worldwide IC package market

ESTIMATED 1989 WORLDWIDE PACKAGING TRENDS



WORLDWIDE PACKAGE CONSUMPTION

1989 - SMT versus TH



SURFACE-MOUNT TECHNOLOGY END-USE SEGMENTS -- 1989

	Japan	North America	Europe	ROW
End Use	Computer	Computer Automotive	Telecom	Consumer
Driving Force	Performance	Speed/Performance	Reliability	Small Size
% of ICs Consumed	39% .	32%	17%	12%
Dominant SMT Approach	SO/Quad/TAB	SO/CC/TAB	SO/TAB	\$O
				Source: Debraset

AGENDA

- Worldwide IC package market
- Emerging technologies analysis

In the next decade,
more performance strides
will be made through improvements
in semiconductor packaging
than through
semiconductor technology

ST ST

Tomorrow,
multichip modules will offer
system-level cost savings
AND
significant performance
improvements

MULTICHIP MODULE (MCM)

A collection of multiple die arranged in a thin-film multilayer interconnect structure that functions as a single integrated circuit, bridging the gap between printed circuit boards and wafer scale integration

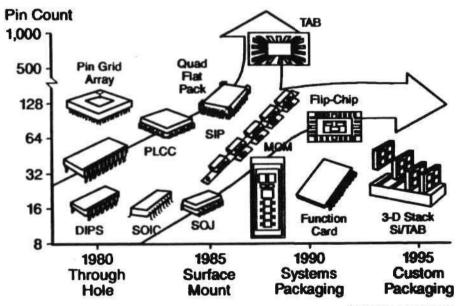
AGENDA

- Worldwide IC package market
- Emerging technologies analysis
- Applications demand analysis and forecast

MCM DRIVERS

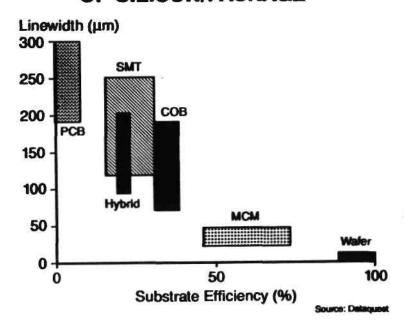
- Supercomputers
- Laptop PCs
- Workstations
- Graphics terminals
- Storage devices
- Switching devices
- Optical communications
- Personal office equipment
- Portable communications
- Satellite communications

PACKAGING ROAD MAP

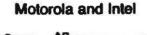


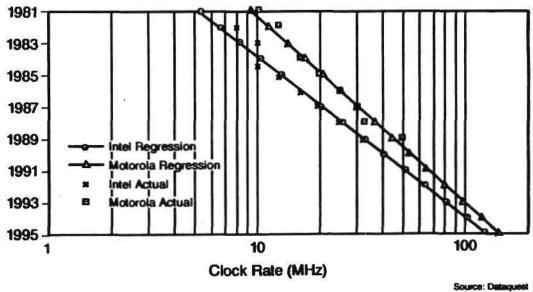
Source: Texas Instruments

PACKAGING EFFICIENCY AREA OF SILICON/PACKAGE



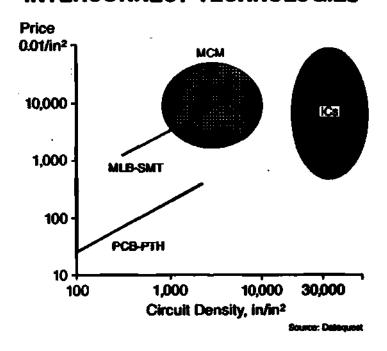
MICROPROCESSOR CLOCK RATES





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INTERCONNECT TECHNOLOGIES



MULTICHIP MODULE ACTIVITY

Advanced Packaging Systems
Alcoa
British Aerospace
Holz Industries
Hughes Aircraft
ICI Array Technology
IDT
Kyocera
Mars Electronics
Midway
Mosaic
Multichip Technology

N + 1
Nara
N-Chip
Oki
Polycon
Polylithics
Raychem
Rogers
Silicon Connections
Thorn EMI
Unistructure

AGENDA

- Worldwide IC package market
- Emerging technologies analysis
- Applications demand analysis and forecast
- Strategic issues and opportunities

CRITICAL ISSUES

DESIGN REQUIREMENTS

- SIMULATION OF MULTICHIP DESIGNS
- TEST PROGRAM GENERATION
- COMPLETE SOFTWARE DESIGN VERIFICATION REQUIRED

CRITICAL ISSUES

MATERIALS REQUIREMENTS

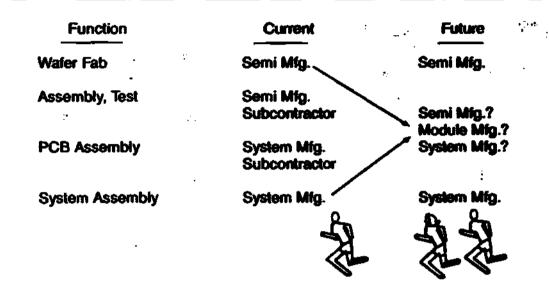
- SUBSTRATE TECHNOLOGY
- INTERCONNECT TECHNOLOGY
- HEAT DISSIPATION REQUIREMENTS
- COST/PERFORMANCE TRADE-OFFS
- STANDARDS

CRITICAL ISSUES

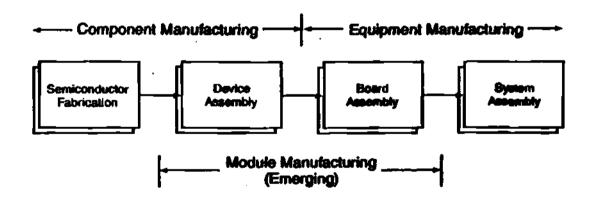
MANUFACTURING REQUIREMENTS

- CRITICAL DIMENSIONS/TOLERANCES
- FLEXIBLE MANUFACTURING.
- MAKE/BUY ALTERNATIVE
- PPM QUALITY VS REWORK

MULTICHIP MODULES WILL CREATE A WHOLE NEW CLASS OF COMPANY



THE ELECTRONICS MANUFACTURING CHAIN



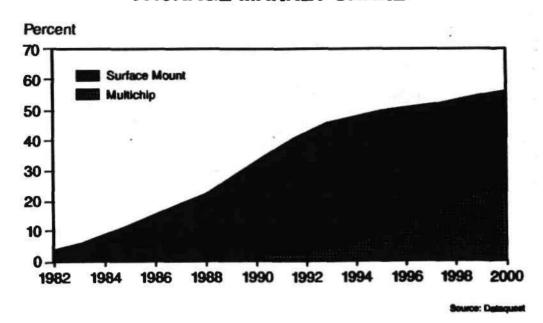
MULTICHIP MODULES ARE COMING

- Semiconductor clock rates will push above 50 MHz in near future
- Multichip modules provide means of taking advantage of these clock rates
- Price premiums in marketplace will support development of the technology
- Surface mount has prepared market to accept packaging innovations

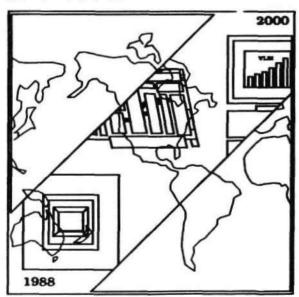
MULTICHIP MODULES WILL CHANGE THE INDUSTRY

- Semiconductor and PCB assembly will be combined
- Leading semiconductor manufacturers will sell modules
- Opportunity will be created for module manufacturers
- System houses will license module technology
- Multichip module users will win in their markets

PACKAGE MARKET SHARE



Worldwide VLSI Packaging Issues and Trends



A multiclient study examining existing and emerging VLSI packaging trends.

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